CLAIMS

What is claimed is:

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1.	A process	chamber	airflow	system,	comprising
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- a blower suitable for creating an initial flow of air suitable for circulation in a process
- 3 chamber;
- a plenum capable of receiving the initial flow of air; wherein the plenum is connected to
- 5 the blower and the process chamber; and
- an air diffuser, connected to the plenum, wherein the air diffuser contains a plurality of
- holes, such that the initial flow of air through the plenum is reduced.
- 1 2. The process chamber airflow system of claim 1, wherein the air diffuser further
- 2 comprises:
- a means for securing the air diffuser to the plenum.
- 1 3. The process chamber airflow system of claim 1, wherein the reduction in airflow
- 2 is sufficient to cause the initial airflow to be distributed uniformly through the plurality of
- 3 holes in the air diffuser.
- 1 4. The process chamber airflow system as claimed in claim 3, wherein the air
- diffuser is capable of eliminating initial airflow turbulence entering the plenum from an
- 3 air filter.
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- 1 5. The process chamber airflow system of claim 1, further comprising a filter
- 2 disposed between the blower and the plenum.
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- 1 6. The process chamber airflow system as claimed in claim 5, wherein an individual
- 2 hole, included in the plurality of holes, cross-sectional area varies.

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7. The process chamber airflow system of claim 1, wherein the air diffuser is capable of dissipating static charges.

1 8. The process chamber airflow system of claim 1, wherein the air diffuser's

- 2 plurality of holes are uniformly distributed throughout the air diffuser.
- 1 9. The process chamber airflow system of claim 1, wherein the air diffuser is capable of being disposed on one side of a generally cubic chamber of a semiconductor
- 3 production device.
- 1 10. The process chamber airflow system of claim 1, wherein the chamber is suitable for utilization in microchip production.
- 1 11. The process chamber airflow system of claim 1, wherein the air diffuser is capable of diffusing air such that contaminate particles are not entrained in the chamber airflow.
- 1 12. The process chamber airflow system of claim 1, wherein the plurality of holes 2 range in size from 0.125 inches to 0.5 inches.
- 1 13. An air diffuser for utilization in a process chamber, comprising
- 2 a means for securing the air diffuser to the process chamber; and
- a plate with a first side and a second side, connected to the securing means, wherein the
- 4 plate includes a plurality of holes penetrating the first and the second sides; wherein the
- 5 plurality of holes are uniformly dispersed throughout the plate; wherein the plurality of
- 6 holes are sufficient to cause the first side of plate to experience a first pressure and the
- second side to experience a pressure lower then the first pressure when the plate is
- 8 disposed in an airflow.

- 1 14. The air diffuser of claim 13, wherein the plurality of holes has a total cross-
- 2 sectional area lower then that of an inlet supplying the airflow.

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- 1 15. The air diffuser of claim 13, wherein the change in pressure between the first and
- 2 the second sides of the plate is sufficient to distribute the airflow through the entire
- 3 plurality of holes.

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- 1 16. The process chamber airflow system of claim 13, further comprising a filter
- 2 disposed between the blower and the plenum.

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- 1 17. The process chamber airflow system as claimed in claim 13 wherein an individual
- 2 hole, included in the plurality of holes, cross-sectional area varies.

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- 1 18. The air diffuser of claim 13, wherein the plate is capable of dissipating static
- 2 charges.

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- 1 19. The air diffuser of claim 13, wherein the air diffuser is capable of diffusing air
- with a substantially laminar flow.

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- 1 20. The air diffuser of claim 13, wherein the plurality of holes range in size from
- 2 0.125 inches to 0.5 inches.

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- 1 21. A method of providing substantially laminar airflow in a process chamber,
- 2 comprising:
- 3 generating an initial flow of air with an initial cross-sectional area;
- disposing an air diffuser with a plurality of uniformly spaced hole in the airflow;
- 5 wherein a total cross-sectional area of the plurality of holes is less then the initial cross-
- 6 sectional area;

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- creating a back-pressure of air due to the reduction in the cross-sectional area through the 7 plurality of holes; 8
- dispersing a portion of the initial airflow uniformly across the air diffuser; 9
- providing uniform airflow through the plurality of holes included in the air diffuser, to the 10 process chamber.